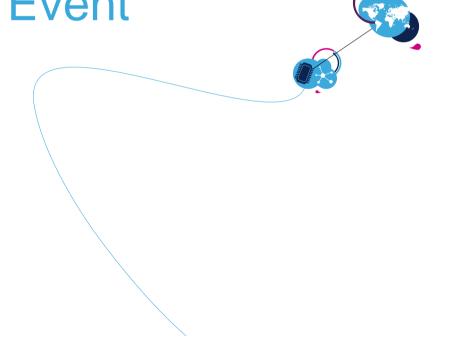


Investor and Media Event

Barcelona, February 26th 2013



Mobile world Congress 2013



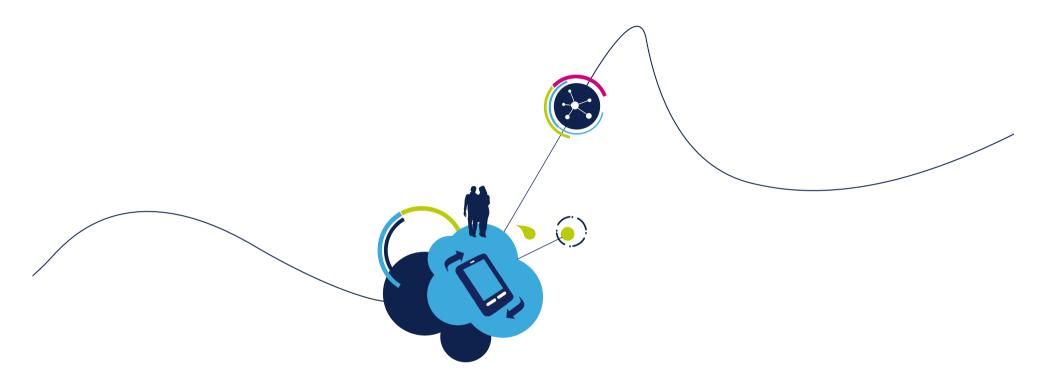
Forward Looking Statements

- Some of the statements contained in this release that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance or events to differ materially from those anticipated by such statements, due to, among other factors:
 - future risks to our core business as well as our ability to accurately estimate our share of costs and the required cash resources which ensue from our decision to exit ST-Ericsson;
 - · our ability to competitively address market demand for the products which we design manufacture and sell;
 - changes in the market for our products, including the actual demand for products where we have achieved design wins and/or demand for applications where we are targeting growth, which is also dependent on our customers' ability to successfully compete in the application markets they serve with our products;
 - our ability in periods of reduced market demand or visibility, to reduce our expenses as required, as well as our ability to operate our manufacturing facilities at sufficient levels with existing process technologies to cover our fixed operating costs;
 - our ability, in an intensively competitive environment, to identify and allocate necessary design resources to successfully develop and secure customer acceptance for new products meeting their expectations;
 - · our ability to achieve our pricing expectations for high-volume supplies of new products in whose development we have been, or are currently, investing;
 - the financial impact of obsolete or excess inventories if actual demand differs from our expectations;
 - our ability to maintain or improve our competitiveness especially in light of volatility in the foreign exchange markets and, more particularly, in the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;
 - the impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;
 - restructuring charges and associated cost savings that differ in amount or timing from our estimates;
 - changes in our overall tax position as a result of changes in tax laws, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;
 - · natural events such as severe weather, earthquakes, tsunami, volcano eruptions or other acts of nature, health risks and epidemics in locations where we, our customers or our suppliers operate;
 - changes in economic, social, political or infrastructure conditions in the locations where we, our customers or our suppliers operate including as a result of macro-economic or regional events, military conflict, social unrest or terrorist activities:
 - · availability and costs of raw materials, utilities, third-party manufacturing services, or other supplies required by our operations;
 - the outcome of ongoing litigation as well as any new litigation to which we may become a defendant;
 - product warranty or liability claims based on epidemic, security or delivery failures or recalls by our customers for a product containing one of our parts or claims arising out of breaches of our information technology systems.

Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.

Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2011, as filed with the SEC on March 5, 2012. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.





ST in wireless



ST's new strategy 4



The new ST – continued focus on wireless



Sense & Power and Automotive Products



- MEMS and Sensors
- Power Discrete and Modules
- Advanced Analog, Power Management and Standard ICs
- Automotive products
 - General Purpose MCUs and Secure MCUs
 - Application Processors and Digital Consumer products
 - Imaging ICs and Modules
 - Digital ASICs

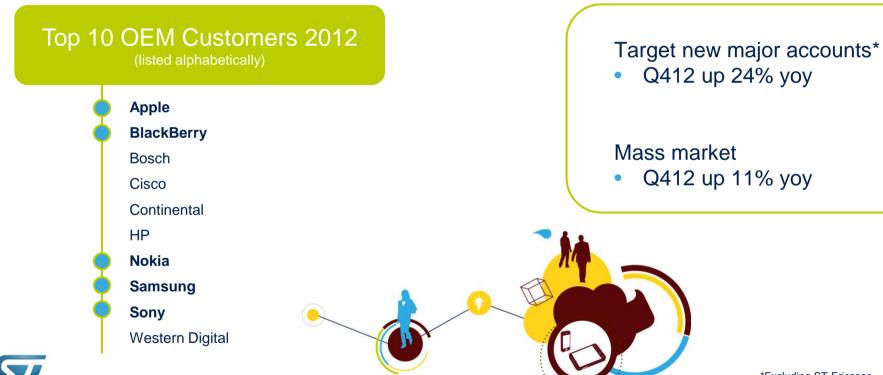
Embedded Processing **Solutions**





ST customer initiatives 6

5 of our top 10 customer are in wireless





*Excluding ST-Ericsson

Cellphones evolve _____



Aware

Power efficient

Intuitive

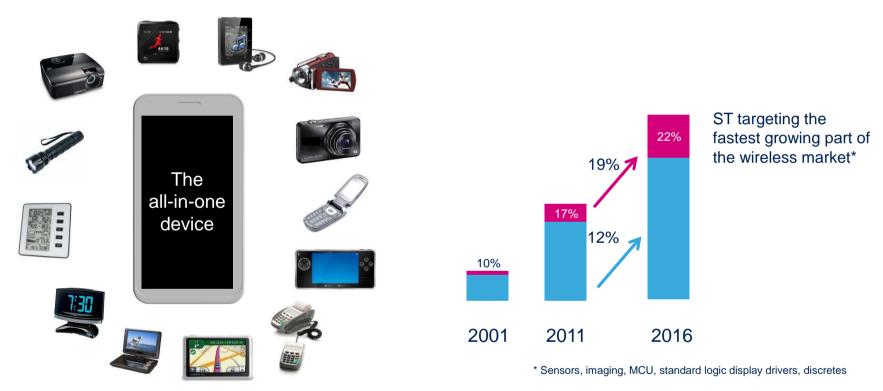
Intelligent

Networked

Secure

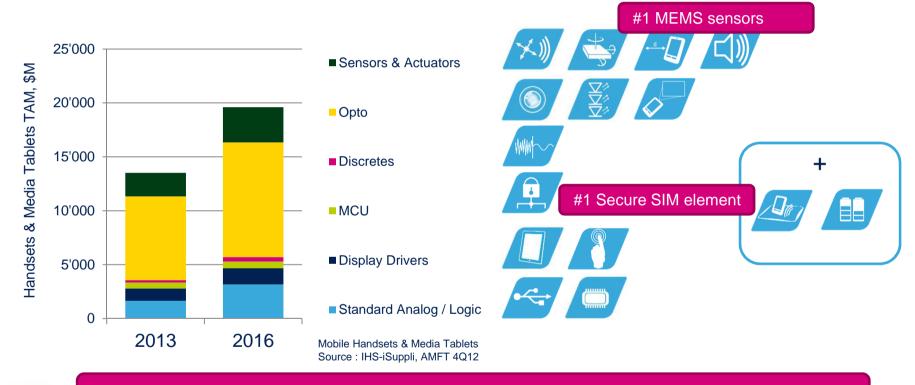


...and so do the components



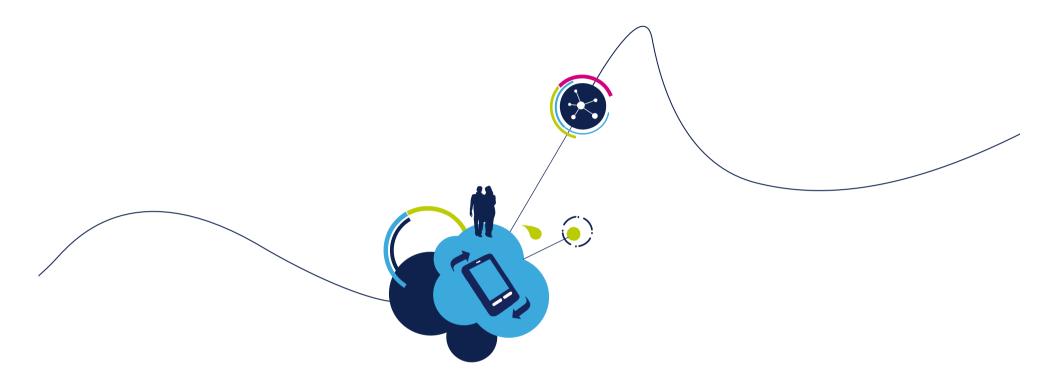
Mobile Handsets & Media Tablets Source: IHS-iSuppli, AMFT 4Q12







Targeting areas where we lead or will lead



What is ST doing for wireless?



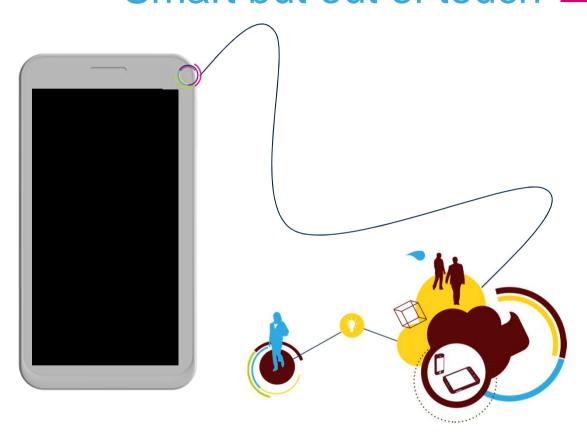
Smart but out of touch ______

This phone is smart

but it's a bit out of touch

That's where ST can help...

Augmenting your mobile experience





Making your phone your secure wallet ________







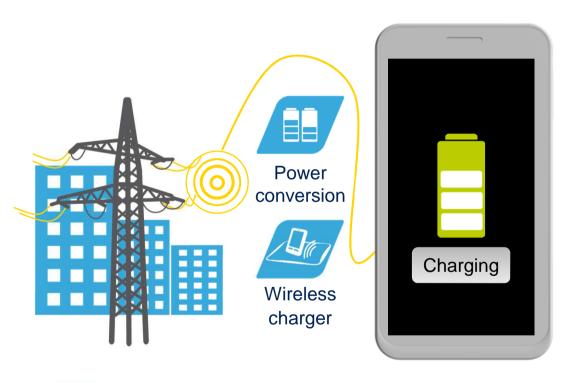


- ST number 1 in SIM Secure Element*
- **Embedded Secure Element** deployed in latest Android devices supporting Google Wallet
- NFC controller deployed in **Android Smartphones**
 - Stacking with embedded secure element, offering complete solution





Connecting you to the power you need 131



- Largest mobile power management IP portfolio
- High-efficiency switching battery charger solutions
- Innovative battery monitoring for reliable charge prediction
- Qi compliant wireless charging solutions



Bringing your display to life 14



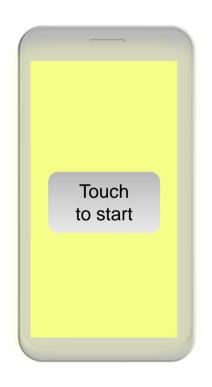




- Leading in energy efficiency and miniaturization for brighter displays and longer battery life
- Leader in AMOLED power supply ICs (73% market share 2012)
- New high frequency backlight ICs for LED brightness control
- Compact, high efficiency, high power, Flash/Torch LED Drivers







- Portfolio of resistive and capacitive controllers - single to multi-touch
- Efficient and safe high voltage generation for haptic feedback
- Hovering and Proximity for "3D touch-less" interaction
 - Finger tracking with water on screen
 - Operation with gloves
 - Drawing with passive or active pen

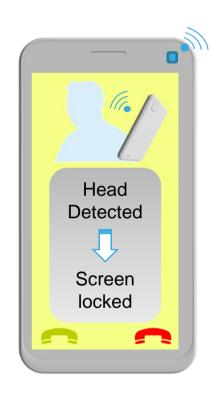




Knowing when you are close 161

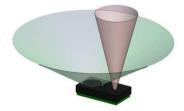


All-in-one proximity and ambient light sensor





- Unique FlightSense™ ranging technology based on time of flight measurement
- Fast, accurate, absolute distance measurement independent of target object characteristics
 - Prevents "face hang-up"
- Enables innovative gesture-based user interaction





Viewing the world around you ______







- Over 20 years of expertise in **CMOS** imaging
- An integrated technology leader in imaging, covering image sensing beyond visible light wavelengths
- Developing innovative imaging solutions in partnership with customers





Sharing your experiences 181





- Revolutionary laser-based MEMS mirror projection technology
- Smaller, lighter and more flexible than competing technologies
- Easy focus free operation
- Amazing vibrant colors projected up to 20" picture size





Enabling an amazing listening experience

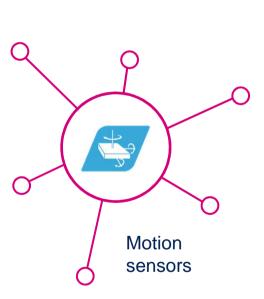




- Audio and Sound enhanced by: Microphone-Array for Voice **Processing**
- **MEMS Microphones**
 - Small size, high sound quality
 - Reliable and affordable
 - 60 million shipped in 2012
- Sampling Second-Generation HD-PA™ Technology from Soundchip
- High efficiency Class G and Class H audio amplifiers



Keeping up with your every movement 201





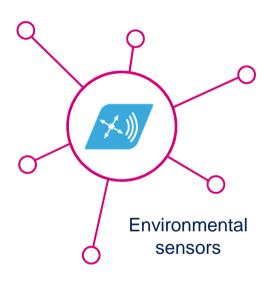


- Enabler and market leader in MEMS sensors for mobile and consumer
- Over 3Bn motion MEMS shipped
- Integrated in Windows 8
- Leading supplier in all major portable OS's
- Own manufacturing & packaging





Sensing the world around you 21





- Complete set of environmental sensors with sensor software
- Provide high precision humidity, temperature and barometric pressure sensing
- World's smallest pressure sensor
- Low power for mobile and battery powered applications







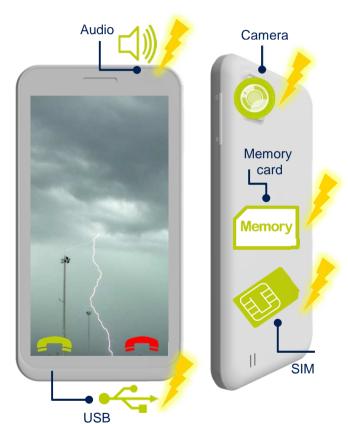
Protecting your device, transferring your data 22



Protection and EMI filtering devices



High speed interface



- Complete range of ESD and **EMI** protection
- 1st IPAD™ integrated devices, combining resistors, capacitors, inductors, ESD diodes and multiple other functions in one package
- USB On-The-Go support
- Micro USB switch for automatic identification and configuration

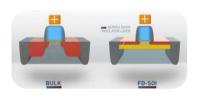


FD-SOI-Innovation for wireless and beyond 23

Faster



Transistors run at 30% higher frequencies than bulk CMOS enabling faster processors





Transistors are more power efficient than bulk CMOS with lower leakage and much wider range of operation points using up to 50% less power



Manufacturing process for FD-SOI is much simpler than alternatives and makes extensive use of existing fab infrastructure

Design porting from bulk is simple and fast





- The new ST is firmly focused on the wireless market
- Targeting the fastest growing areas of wireless semiconductors
- Already in many leading positions
- Innovating to take leadership in new segments
- Offering solutions beyond semiconductors

Targeting and enabling the new trends and needs ... for an augmented mobile future



26

Visit us at the Fira



57





Hall 7 E110





Backlight drivers







Proximity and ambient light sensors



Imaging solutions

FD-SOI







Environmental sensors



Motion sensors



Audio processors MEMS microphones Audio amplifiers



Ultra mobile Projector



Image sensors





Q&A session 27





Benedetto Vigna

Executive Vice President

General Manager, Analog, MEMS & Sensors Group Industrial & Multisegment Sector

Claude Dardanne

Executive Vice President

General Manager,
Microcontroller, Memory &
Secure MCU Group
Industrial & Multisegment Sector

Paul Grimme

Executive Vice President

General Manager, Sales & Marketing, Europe, Middle East and Africa





